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MURF820

Advance Information

SWITCHMODE™ Power Rectifier

Designed for use in switching power supplies, inverters and as free wheeling diodes, these state−of−the−art devices have the following features:

- Ultrafast 35 ns Recovery Times
- 150°C Operating Junction Temperature
- Epoxy Meets UL94, V_O @ 1/8″
- High Temperature Glass Passivated Junction
- Low Leakage Specified @ 150°C Case Temperature
- Current Derating @ Both Case and Ambient Temperatures
- Electrically Isolated. No Isolation Hardware Required.
- UL Recognized File #E69369(1)

Mechanical Characteristics

- Case: Epoxy, Molded
- Weight: 1.9 grams (approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead Temperature for Soldering Purposes: 260°C Max. for 10 Seconds

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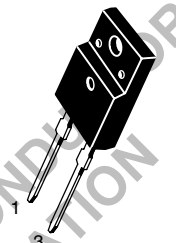
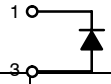
ULTRAFAST RECTIFIER
8 AMPERES, 200 VOLTS



CASE 221E−01
ISOLATED TO−220



MAXIMUM RATINGS

Rating		Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage		V_{RRM} V_{RWM} V_R	200	Volts
Average Rectified Forward Current (Rated V_R), T_C = 150°C		$I_{F(AV)}$	8	Amps
Peak Repetitive Forward Current (Rated V_R, Square Wave, 20 kHz), T_C = 150°C		I_{FM}	16	Amps
Non−repetitive Peak Surge Current (Surge applied at rated load conditions halfwave, single phase, 60 Hz)		I_{FSM}	100	Amps
Operating Junction and Storage Temperature		T_J, T_{stg}	− 65 to +150	°C
RMS Isolation Voltage (t = 1 second, R.H. ≤ 30%, T_A = 25°C) (2)	Per Figure 3 Per Figure 4 (1) Per Figure 5	V_{iso1} V_{iso2} V_{iso3}	4500 3500 1500	Volts

THERMAL CHARACTERISTICS

Maximum Thermal Resistance, Junction to Case	$R_{\theta JC}$	4.2	°C/W
Lead Temperature for Soldering Purposes: 1/8″ from Case for 5 seconds	T_L	260	°C

(1) UL Recognized mounting method is per Figure 4.
(2) Proper strike and creepage distance must be provided.

This document contains information on a new product. Specifications and information herein are subject to change without notice.

ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Maximum Instantaneous Forward Voltage (3) (i_F = 8.0 Amp, T_C = 150°C) (i_F = 8.0 Amp, T_C = 25°C)	v_F	 0.895 0.975	Volts
Maximum Instantaneous Reverse Current (3) (Rated dc Voltage, T_C = 150°C) (Rated dc Voltage, T_C = 25°C)	i_R	 250 5.0	μA
Maximum Reverse Recovery Time (I_F = 1.0 Amp, di/dt = 50 Amp/μs) (I_F = 0.5 Amp, i_R = 1.0 Amp, I_{REC} = 0.25 Amp)	t_{rr}	 35 25	ns

(3) Pulse Test: Pulse Width = 300 μs, Duty Cycle ≤ 2.0%.

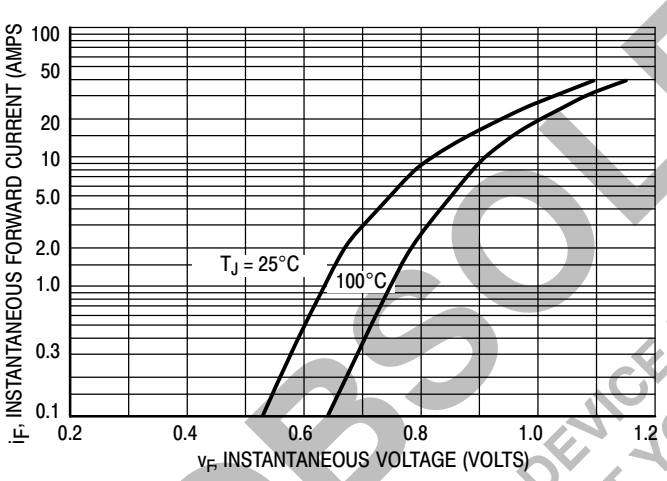


Figure 1. Typical Forward Voltage

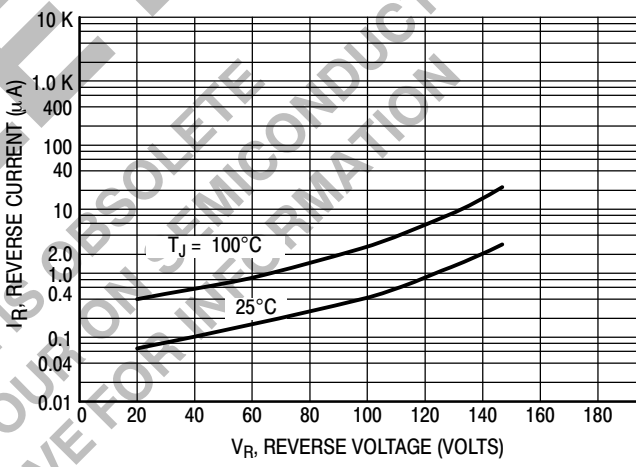


Figure 2. Typical Reverse Leakage Current*

TEST CONDITIONS FOR ISOLATION TESTS*

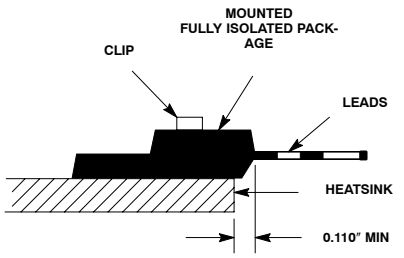


Figure 3. Clip Mounting Position for Isolation Test Number 1

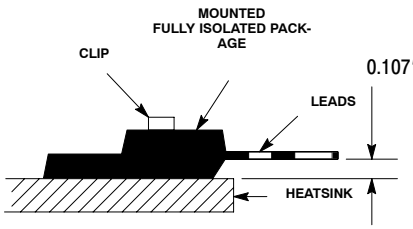


Figure 4. Clip Mounting Position for Isolation Test Number 2

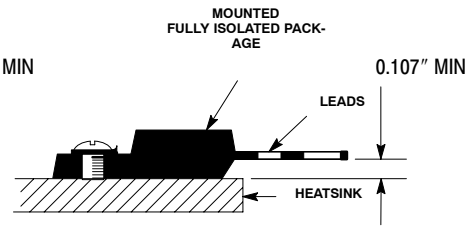
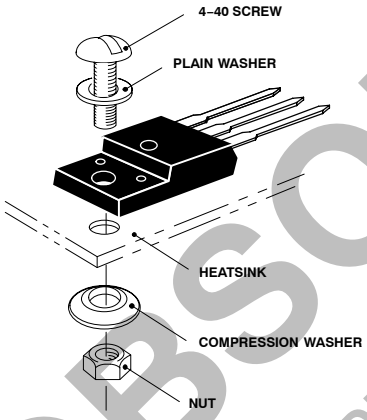


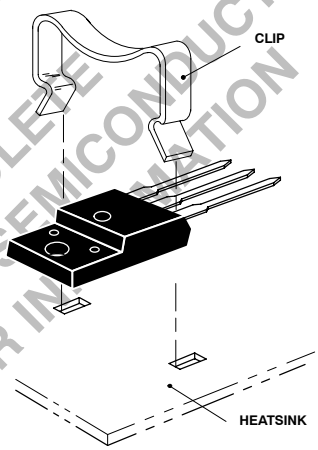
Figure 5. Screw Mounting Position for Isolation Test Number 3

* Measurement made between leads and heatsink with all leads shorted together.

MOUNTING INFORMATION**



6a. Screw–Mounted



6b. Clip–Mounted

Figure 6. Typical Mounting Techniques

Laboratory tests on a limited number of samples indicate, when using the screw and compression washer mounting technique, a screw torque of 6 to 8 in · lbs is sufficient to provide maximum power dissipation capability. The compression washer helps to maintain a constant pressure on the package over time and during large temperature excursions.

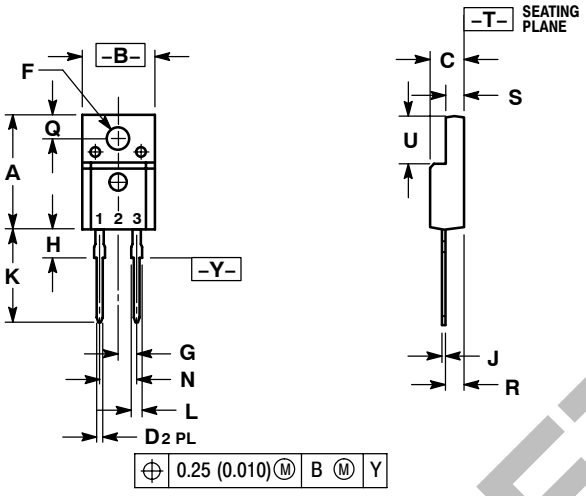
Destructive laboratory tests show that using a hex head 4–40 screw, without washers, and applying a torque in excess of 20 in · lbs will cause the plastic to crack around the mounting hole, resulting in a loss of isolation capability.

Additional tests on slotted 4–40 screws indicate that the screw slot fails between 15 to 20 in · lbs without adversely affecting the package. However, in order to positively ensure the package integrity of the fully isolated device, Motorola does not recommend exceeding 10 in · lbs of mounting torque under any mounting conditions.

**For more information about mounting power semiconductors see Application Note AN1040.

PACKAGE DIMENSIONS

CASE 221E−01
ISSUE O



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.621	0.629	15.78	15.97
B	0.394	0.402	10.01	10.21
C	0.181	0.189	4.60	4.80
D	0.026	0.034	0.67	0.86
F	0.121	0.129	3.08	3.27
G	0.100 BSC		2.54 BSC	
H	0.123	0.129	3.13	3.27
J	0.018	0.025	0.46	0.64
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.14	1.52
N	0.200 BSC		5.08 BSC	
Q	0.126	0.134	3.21	3.40
R	0.107	0.111	2.72	2.81
S	0.096	0.104	2.44	2.64
U	0.259	0.267	6.58	6.78

STYLE 1:
PIN 1. CATHODE
2. N/A
3. ANODE

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